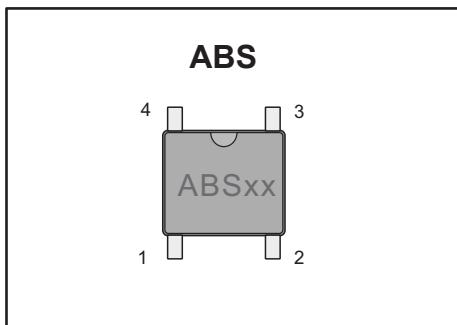


## SINGLE PHASE GLASS PASSIVATED BRIDGE RECTIFIERS

### PINNING

PIN	DESCRIPTION
1	Input Pin ( ~ )
2	Input Pin ( ~ )
3	Output Anode ( + )
4	Output Cathode ( - )



### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed 250°C/10 seconds at terminals

### Mechanical Data

- ◆ **Case:** Molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Polarity symbol marking on body
- ◆ **Mounting Position:** Any
- ◆ **Weight :** 0.004 ounce, 0.12 grams

## Maximum Ratings And Electrical Characteristics

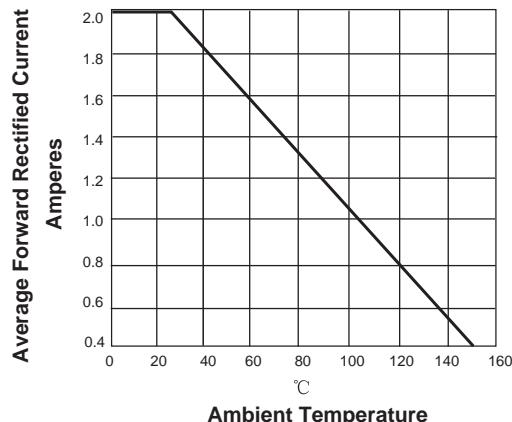
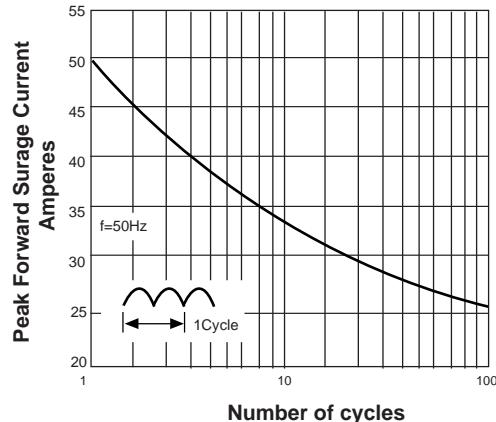
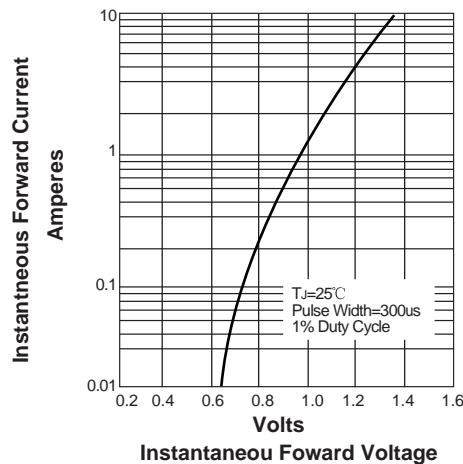
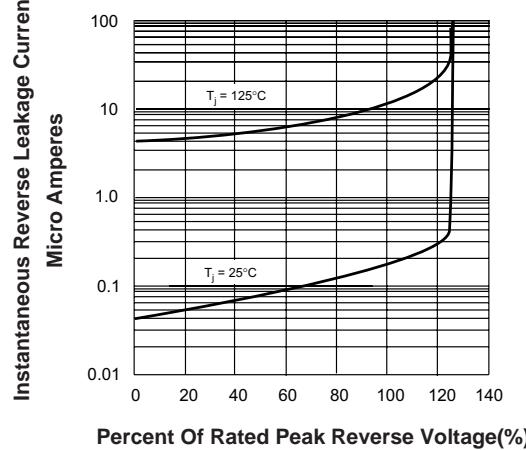
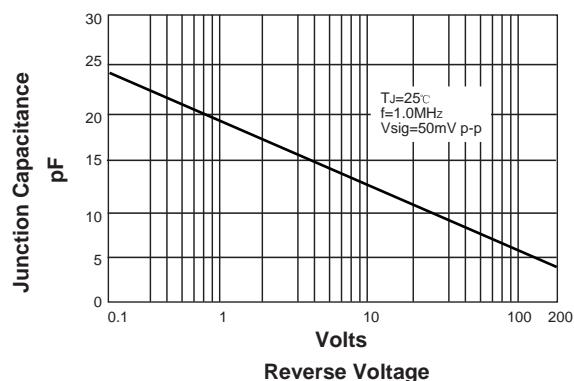
Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz,resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ABS22	ABS24	ABS26	ABS28	ABS210	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	1000	VOLTS
Maximum RMS voltage	$V_{RMS}$	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	$V_{DC}$	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at $T_A=30^\circ C$ On glass-epoxy P.C.B (Note 1)	$I_{(AV)}$	2.0					Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	50.0					Amps
Maximum instantaneous forward voltage at 2.0A	$V_F$	1.1					Volts
Maximum DC reverse current $T_A = 25^\circ C$ at rated DC blocking voltage $T_A = 125^\circ C$	$I_R$	5.0 500					$\mu A$
Typical junction capacitance (Note 3)	$C_J$	15.0					pF
Typical thermal resistance	$R_{QJA}$	75.0					$^\circ C/W$
Operating junction and storage temperature range	$T_{J,T_{STG}}$	-55 to +150					$^\circ C$

**Note:**1.Mounted on glass epoxy PC board with 1.3\*1.3mm solder pad

2.Mounted on aluminum substrate PC board with 1.3\*1.3mm solder pad

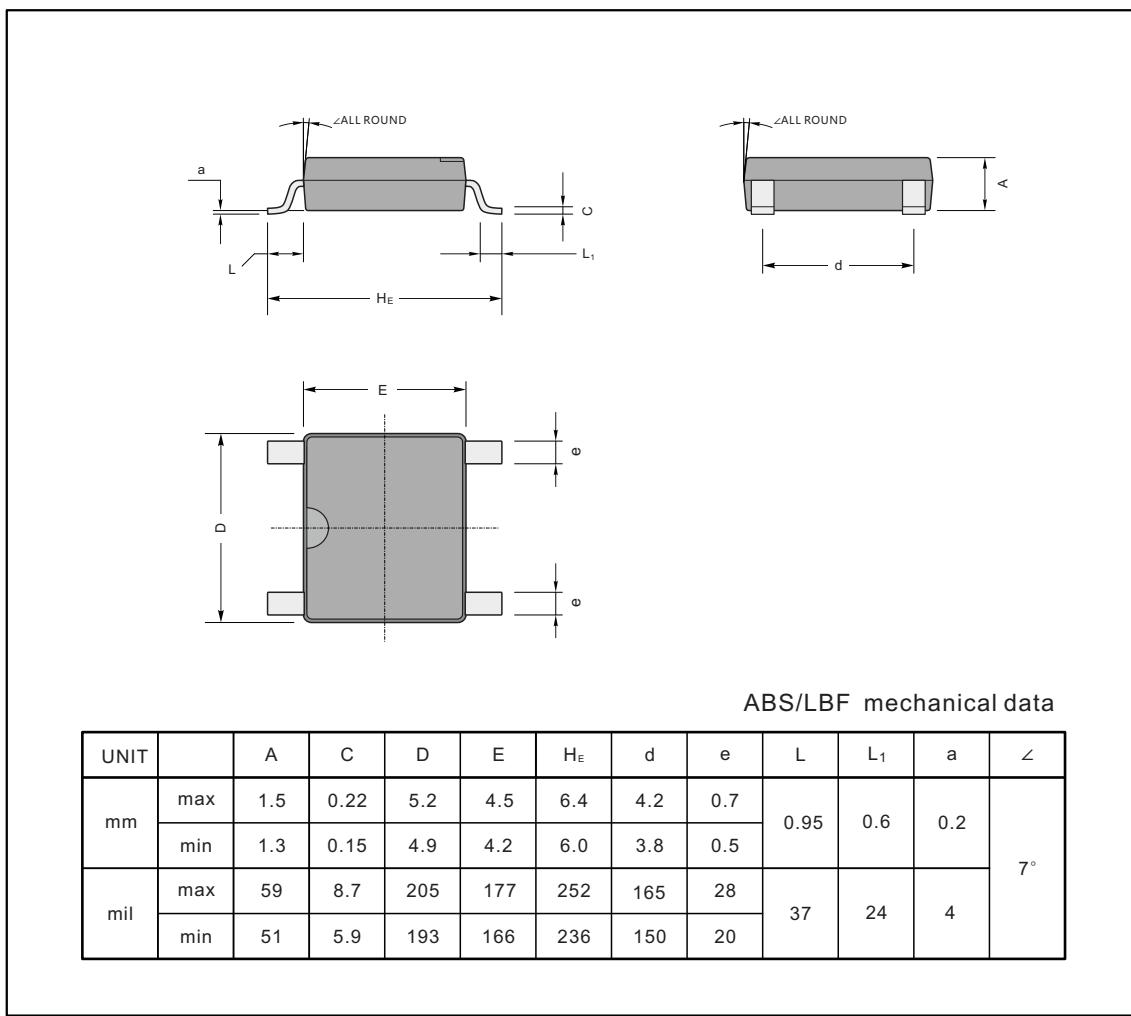
3.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

**FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT**

**FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG**

**FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS**

**FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS**

**FIG. 5-TYPICAL JUNCTION CAPACITANCE**


## PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

**ABS**



ABS/LBF mechanical data

UNIT		A	C	D	E	H <sub>E</sub>	d	e	L	L <sub>1</sub>	a	∠
mm	max	1.5	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.3	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	59	8.7	205	177	252	165	28	37	24	4	7°
	min	51	5.9	193	166	236	150	20				

### The recommended mounting pad size

